

# MPS 2 R300 CV

Safe and easy grinding semiconductor material

Grinding-

machines

Genauigkeits  
Maschinenbau  
Nürnberg GmbH

# G&N



Fig. Grinding area

## Technical Data

<b>AC motor</b>	2,2 kW
<b>Spindle speed</b>	500 - 3000 min <sup>-1</sup>
<b>Elec. connection</b>	3,2 kW
<b>Rotary table</b>	
Diameter	ø 300 mm
Rotational speed	1 - 40 min <sup>-1</sup>
Axial run-out	< 3 µm
<b>Grinding wheel</b>	
CBN/Diamond	ø 175 mm

<b>Vacuum chucks</b>	18 x 2" ; 8 x 3" 5 x 4" ; 3 x 5" 2 x 6"
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<b>Hydr. rough adjustment</b>	
Range	180 mm

<b>Fine infeed</b>	
Range	12 mm
Min. step	1 µm

<b>Weight</b>	780 kg
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<b>Dimensions (l x w x h) machine</b>	1400x1000x1850 mm
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## Application

Rough and finish grinding of silicon, GaAs, sapphire and other semi-conductor materials at highest flatness accuracy

## Features

- PLC control SIMATIC S7-1200
- Frequency inverter
- Rotary table
- Hydraulic unit
- Automatic fine infeed
- Programmable grinding cycles (3 different types of programs)
- Touch panel TP 900 comfort
- Splash guard
- Hand shower
- Vacuum clamping

## Characteristic

Fully automatic vertical high precision surface grinder with vertical spindle, cup wheel, fully enclosed grinding area, frequency controlled rotary table and grinding spindle, vacuum chucks and high precision automatic infeed.

## Accessories (optional)

- Wet grinding equipment
- In-process measuring unit
- CBN- and diamond grinding wheels
- Vacuum chucks